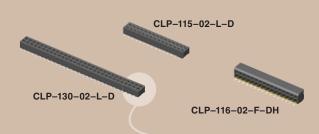


(1,27 mm) .050"

CLP SERIES





OW PROFILE DUAL WIPE SOCKET

CLP-107-02-F-D-P

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over

50μ" (1,27 μm) Ni **Current Rating:** 3.3 A per pin (2 pins powered)

Operating Temp Range: -55°C to +125°C

Contact Resistance: 10 mQ

Insertion Depth:

Top Entry = (1,40 mm) .055" minimum, Bottom Entry = (2,41 mm) .095" minimum plus board thickness DH Entry = (2,31 mm) .091" to (2,67 mm) .105"

Insertion Force:

(Single contact only) 3.8 oz (1,05 N) average

Normal Force: 60 grams (0,59 N) average Withdrawal Force: (Single contact only) 2 oz (0,56 N) average

Max Cycles: 100 with 10μ" (0,25 μm) Au RoHS Compliant:

Processing:

Lead-Free Solderable:

SMT Lead Coplanarity:

(0,10 mm) .004" max (02-35) (0,15 mm) .006" max (36-50)

RECOGNITIONS

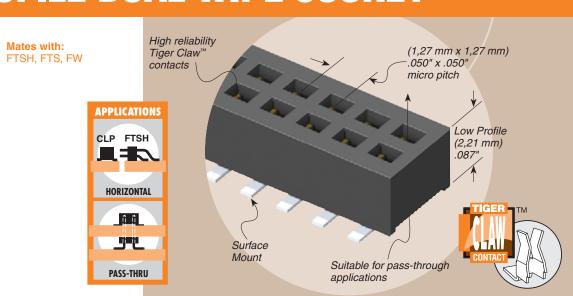
For complete scope of recognitions see www.samtec.com/quality

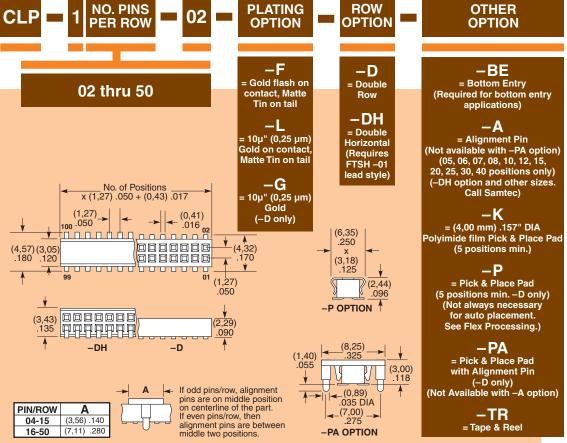


ALSO AVAILABLE (MOQ Required)

- Single row
- Other Platings Contact Samtec.

Note: Some sizes, styles and options are non-standard. non-returnable.





Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM